



Special Issue on
**Chemical Functionalization, Self-Assembly, and
Applications of Nanomaterials and Nanocomposites
2014**

CALL FOR PAPERS

Nanomaterials and nanocomposites have held considerable interest for application in various areas due to their unique properties. The functionalization and bottom-up assemblies of nanomaterials and subsequent applications of well-defined micro/nanostructures have multiple important impacts upon nanoscience and nanotechnology. The detailed understanding and control of the driving force for the assembly process make it possible to tailor the assembly process both at interface and in solution. The sophisticated nanostructures with multiple components have deepened the insight of nanomaterials and enriched the content of supramolecular chemistry. It can be predicted that, as the growth of understanding of the rules in the nanoscale, our dream to manipulate molecules to achieve the precisely tailored organic/inorganic nanostructures could be realized in the future.

In this special issue, we invite the submission of original research articles as well as review articles that will focus on various nanoscale bottom-up assembly processes, functionalization, and their potential applications in wide fields. We are particularly interested in articles describing new nanostructured materials/composites and the regulation of their interesting properties.

Potential topics include, but are not limited to:

- ▶ Chemical functionalization of nanomaterials and nanocomposites
- ▶ Bottom-up assembly techniques of nanostructured materials
- ▶ Preparation of 1-, 2-, and 3-dimensional nanomaterials and nanocomposites
- ▶ Characterization of nanostructures and nanocomposites
- ▶ Applications of nanomaterials and nanocomposites for catalytic, optical, environmental, medical, energy, and other applications
- ▶ Research progress of novel nanomaterials and nanocomposites in focus (quantum dot, graphene, carbon nanotubes, etc.)

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First Round of Reviews

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